

Date	User	Film	Recipe	Substrate	Coat time		Thickness	JAW EC-400 (Woolam S.E.)		Avg Index	Index+1%	Index-1%	Dep.rate	Avg.Dep. Rate		Avg+3%	Avg-3%	HF e.r.	Stress	Avg			LPD (light point defects)		Comment	Mile Silva
					T	min		sec	Index @ 632.8nm					Index @ 1550nm	Rate					Rate	Stress	Avg+50%	Avg-50%	before dep.		
300°C																										
min																										
sec																										
(Å)																										
nm/min																										
nm/min																										
nm/min																										
nm/min																										
nm/min																										
MPa																										
before dep.																										
after dep.																										
4"Si wafer, placed in the center of platen																										
Mike Silva																										
LS Nitride 2																										
01/17/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2489.91	1.932	1.899	1.932	1.952	1.913	4.34	4.33	4.46	4.20	45.13	-0.99	-26.31	-39.47	-13.16	59	294	New recipe		
01/30/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2533.04	1.933	1.899	1.932	1.952	1.913	4.26	4.33	4.46	4.20			-26.31	-39.47	-13.16			Film less uniform		
02/03/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2437.59	1.932	1.899	1.932	1.952	1.913	4.43	4.33	4.46	4.20	43.75	-19.07	-26.31	-39.47	-13.16	104	437	Film OK		
02/18/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2469.99	1.931	1.898	1.932	1.952	1.913	4.37	4.33	4.46	4.20	41.27	-57.04	-26.31	-39.47	-13.16	15	74	Film less uniform	2/14/14 Silane change	
03/12/14	Biljana	SI3N4	LS Nitride 2	300	10min	1800.00	2544.75	1.932	1.898	1.932	1.952	1.913	4.24	4.33	4.46	4.20	54.74	-28.14	-26.31	-39.47	-13.16	56	99	Film OK		

Avg. Thickness	2495.06	Avg Dep. Rate	4.33	Avg HF e.r	46.22
Avg. Index	1.932	Avg+3%	4.46	Avg Stress	-26.31
Index+1%	1.952	Avg-3%	4.20	Avg+50%	-39.47
Index-1%	1.913			Avg-50%	-13.16

